SemDex

Contactless, fast and precise during process coı

ISIS sentronics

SemDex Mf 201

This most cost-effective fully manual system permits spot-to-spot measurements of (substrate-) layer thicknesses. Wafers up to 8” can be evaluated.

Applications:

- (Substrate-) layer thickness (t > 3 µm)
- Bow/ warp
- Flatness (SBIR, SFQR etc.)
- Topography (Mini-bumps)
- Roughness (R_a > 0.1 µm) kness

Materials:

Substrat-Materials:

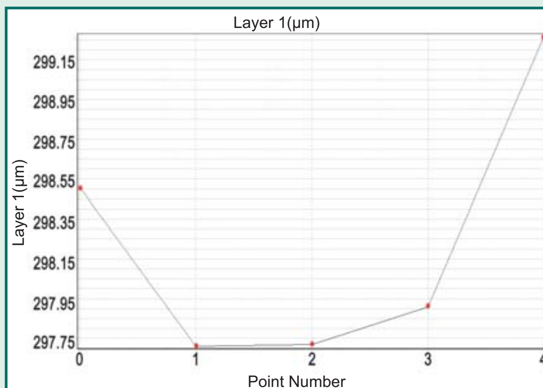
- Silizium
- GaAs
- CdTe
- Glass and others

Thin Layer-Materials:

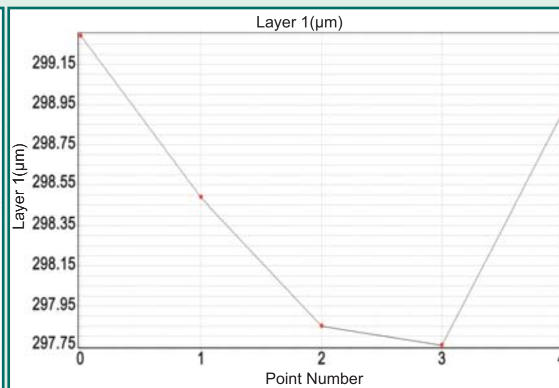
- SOI
- Polyamide
- Photoresist (spin coating)

Your benefits:

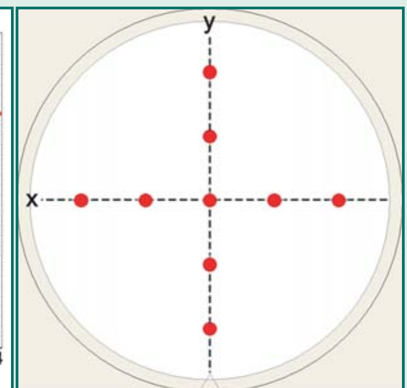
- Contactless measurements in reflection mode
- Very high acquisition rates of up to 16 kHz
- Repeatabilities better than 50 nm
- Near-edge exclusion or fine structures due to small spot size (20 or 5 µm)
- Substrate thickness measurements not affected by tape, bumps etc.
- All different materials measurable: Silicon, InGaAs, InP, SiC, TFT-Glass, Ceramics, Tape, Photoresist, etc.
- (Multiple-) layer thicknesses, bow/ warp and flatness in one scan available
- Negligible shadowing at steep trenches (bumps)
- Automatic beam refocussing at various working heights (multiple chuck)



Measured data in x-direction



Measured data in y-direction



Measured points

ISIS sentronics GmbH · Innstrasse 28 · 68199 Mannheim/ Germany · Tel: 49 (621) 84251-0 · Fax: 49 (621) 84251-200 · www.isis-sentronics.com

Chunson 冲 成 有 限 公 司
JC's Chunson Limited
TEL:+886-2-3234-1279 http://www.chunson.com
FAX:+886-2-3234-7056 E-mail:info@chunson.com